



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-09-30
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32U385CGT6	635B*454XXXZ	A	998Z	2024-09-30
Amount	Unit of measure	Unit type	ST ECOPACK grade	
180	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFP	7x7	48	Gull wing	
Comment	Package : 5B LQFP 48 7x7x1.4 1 0110596			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-27th June 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	635B*454XXXZ		180.1656		6000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	8.722	mg	supplier	die	Silicon (Si)	7440-21-3		8.388	mg	961672	46557.63036
				supplier	metallization	Aluminium (Al)	7429-90-5		0.037	mg	4229	204.7394733
				supplier	metallization	Copper (Cu)	7440-50-8		0.110	mg	12619	610.9263216
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	67	3.243685201
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.019	mg	2148	103.9915793
				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	537	25.99789482
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	67	3.243685201
				supplier	Passivation	Silicon Nitride	12033-89-5		0.026	mg	3021	146.2563133
				supplier	Passivation	Silicon Oxide	7631-86-9		0.136	mg	15640	757.1826349
				supplier	Organic Compounds	Acrylic resin	Proprietary		0.013	mg	70000	69.62337654
Glue epoxy (EN4900GC)	Other Organic Materials	0.179	mg	supplier	Organic Compounds	Polybutadiene derivative	Proprietary		0.004	mg	20000	19.8923933
				supplier	Organic Compounds	Butadiene copolymer	Proprietary		0.003	mg	15000	14.91929497
				supplier	Organic Compounds	Acrylate	Proprietary		0.010	mg	54000	53.7094619
				supplier	Organic Compounds	Epoxy resin	Proprietary		0.005	mg	30000	29.83858994
				supplier	Organic Compounds	Peroxide	Proprietary		0.001	mg	8000	7.956957318
				supplier	Organic Compounds	Additive	Proprietary		0.003	mg	18000	17.90315397
				supplier	Metals	Silver	7440-22-4		0.141	mg	785000	780.7764369
				supplier	Organic Compounds	Epoxy Resin	Proprietary		6.525	mg	55000	36218.51073
Encapsulation (EME-G700LAL-A)	Other Organic Materials	118.642	mg	supplier	Organic Compounds	Phenol Resin	Proprietary		2.491	mg	21000	13828.88592
				supplier	Glass	Silica(Amorphous)A	60676-86-0		94.914	mg	800000	526814.7016
				supplier	Glass	Silica(Amorphous)B	7631-86-9		14.118	mg	119000	78363.68686
				supplier	Organic Compounds	Carbon Black	1333-86-4		0.593	mg	5000	3292.591885
				supplier	Metals	Copper	7440-50-8		0.525	mg	965500	2911.253487
Bonding Wire (Cu)	Bonding Wire	0.543	mg	supplier	Metals	Palladium	7440-05-3		0.017	mg	31000	93.47370077
				supplier	Metals	Gold	7440-57-5		0.002	mg	3500	10.55348235
				supplier	Metals	Tin	7440-31-5		1.078	mg	1000000	5985.574962
Plating anode (Sn)	Other inorganic materials	1.078	mg	supplier	Metals	Copper	7440-50-8		49.595	mg	972450	275274.2764
				supplier	Metals	Iron	7439-89-6		1.153	mg	22600	6397.448348
				supplier	Metals	Zinc	7440-66-6		0.077	mg	1500	424.6094036
				supplier	Metals	Phosphorus	7723-14-0		0.015	mg	300	84.92188073
				supplier	Metals	Silver	7440-22-4		0.158	mg	3100	877.5261009
Leadframe (C194 + Ag)	Copper & its alloys	51.000	mg	supplier	Metals	Lead	7439-92-1		0.003	mg	50	14.15364679
				SVHC	Metals	Lead	7439-92-1		0.003	mg	50	14.15364679